PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data			
1.1 Company	life.augmented	STMicroelectronics International N.V	
1.2 PCI No.		MICROCONTROLLERS/25/15166	
1.3 Title of PCI		JSCC (China) - KOSTAT Carrier Tape & Cover Tape alternative packing material for TQFP7x7 8 QFP10x10 package on listed products.	
1.4 Product Category		STM32C0x, STM32F1x, STM32F2x, STM32F3x, STM32F4x, STM32F7x, STM32G0x, STM32G4x, STM32H5x, STM32H7x, STM32L0x, STM32L1x, STM32L4x, STM32L5x, STM32U0x, STM32U3x, STM32U5x, STM8L0x, STM8L1x, STM8S0x, STM8S1x,STM8S2x, STM8S9x All listed products in Tape & Reel packing only.	
1.5 Issue date		2025-01-27	

2. PCI Team		
2.1 Contact supplier		
2.1.1 Name	PIKE EMMA	
2.1.2 Phone	+44 1628896111	
2.1.3 Email	emma.pike@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Patrick AIDOUNE	
2.1.2 Marketing Manager	Veronique BARLATIER	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change			
3.1 Category	3.2 Type of change	3.3 Manufacturing Location	
Materials	New Indirect material part number (same supplier or different supplier): Boxes, trays, carriers, back grinding tape, wafer mounting tape, mold tape, etc	STATSChipPAC JSCC (China)	

4. Description of change		
	Old	New
4.1 Description	For QFP7X7, QFP10X10 packages - E-PAK carrier tape and cover tape	For QFP7X7 & QFP10X10 packages - E-PAK carrier tape and cover tape (until depletion of current material) Then KOSTAT carrier tape (4-side partial fence) and cover tape.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change		
	Alternate Tape & Reel material with more robust 4-side fence pockets design to further reduce risk of potential bent leads issues during reel handling.	
5.2 Customer Benefit	SERVICE IMPROVEMENT	

6. Marking of parts / traceability of change	
6.1 Description	Traceability ensured by ST internal tools

7. Timing / schedule	
7.1 Date of qualification results	2024-11-27
7.2 Intended start of delivery	2025-04-15
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation			
8.1 Description	15166 GPAM-qualification.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2025-01-27

9. Attachments (additional documentations)

15166 Public product.pdf 15166 GPAM-qualification.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
0.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F030C6T6TR	
	STM32F030C8T6TR	
	STM32F030CCT6TR	
	STM32F051C8T6TR	
	STM32F051K6T6TR	
	STM32F070RBT6TR	
	STM32F072R8T6TR	
	STM32F091CCT6TR	
	STM32F100C8T6BTR	
	STM32F100CBT6BTR	
	STM32F101RBT6TR	
	STM32F101RFT6TR	
	STM32F103C8T6TR	
	STM32F103R8T6TR	
	STM32F103RBT6TR	
	STM32F103RCT6TR	
	STM32F103RDT6TR	
	STM32F103RET6TR	
	STM32F205RBT6TR	
	STM32F205RGT6TR	
	STM32F415RGT6TR	
	STM32G030K8T6TR	
	STM32G070CBT6TR	
	STM32G070KBT6TR	
	STM32G0B0CET6TR	
	STM32L071RZT6TR	
	STM32L100RBT6ATR	
	STM32L100RBT6TR	
	STM32L100RCT6TR	
	STM32L431RBT6TR	
	STM8S003K3T6CTR	
	STM8S005C6T6TR	
	STM8S007C8T6TR	

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